COMMO. GOAMHOD

PATENT APPLICATION

Attorney Docket No.: 01-146 Date: August 30, 2001

24319

PATENT TRADEMARK OFFICE

ATTN: BOX PATENT APPLICATION Commissioner for Patents Washington, D.C. 20231

NEW APPLICATION TRANSMITTAL

Transmitted herewith for filing is the patent application of

Inventor(s): Charles E. May

For (title): Arrangement and Method for Fabricating a Semiconductor Wafer

Enclosed are:

- [x] 2 sheet(s) of drawings (2 sets) (INFORMAL)
- [x] An executed Assignment of the invention to LSI Logic Corporation
- [x] An executed Declaration and Power of Attorney is enclosed
- [] Material information pursuant to 37 CFR §1.56.
- [] It is expressly requested that the U.S. Patent and Trademark Office commence national processing of the above-entitled international application under the provisions of PCT Article 23(2) and 35 USC 371(f).
- [x] Nonpublication Request Under 35 U.S.C. 122(b) (2) (B) (i)
- [x] Return Postcards(2)

Correspondence Address:

Sandeep Jaggi c/o Mark Salvatore LSI Logic Corporation M/S D-106 1551 McCarthy Boulevard Milpitas, California 95035

or Agent of Record

Bradford G. Addison Reg. No. 41,486

The filing fee has been calculated as shown below:

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
TOTAL CLAIMS	20 - 20 =	0	x \$18	00.00
INDEPENDENT CLAIMS	3 - 3 =	0	x \$80	00.00
			BASIC FEE	\$710.00
			FILING FEE	\$710.00

- The Commissioner is hereby authorized to charge the basic filing fee (\$710.00) to Deposit Account No. 12-2252. Two copies of this sheet are enclosed.
- The Commissioner is hereby authorized to charge any fees under 37 CFR [x] §1.16 and 1.17 which may be required during the pendency of the application to Deposit Account No.12-2252.

"Express mail" mailing label number <u>EL904476829US</u> Date of Deposit August 30, 2001 I hereby certify that this correspondence is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and is addressed to the Commissioner of Patents, Box PATENT APPLICATION, Washington, D.C. 20231.

Bradford G. Addison (Name of person mailing application)

(Signature of person mailing application)



NONPUBLICATION REQUEST UNDER 35 U.S.C. 122(b)(2)(B)(i) Title Arrangement and Method for Fabricating a Semiconductor Wafer

Atty Docket Number LSI No.: 01-146

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

August 30, 2001
Date

Bradford G. Addison

Typed or printed name

Signature

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing.**

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant must notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).